

# Intel® Core™2 Duo Processor T6570 (2M Cache, 2.10 GHz, 800 MHz FSB)

- Specifications
- Essentials
- Performance
- Package Specifications
- Advanced Technologies
- Intel® Platform Protection Technology
- Ordering / sSpecs / Steppings

Specifications	
Essentials	
Status	End of Interactive Support
Launch Date	Q2'09
Processor Number	T6570
Cache	2 MB
Instruction Set	64-bit
Embedded Options Available	No
Lithography	45 nm
VID Voltage Range	1.00V-1.250V
Recommended Customer Price	N/A
Datasheet	Link
Performance	
# of Cores	2
Processor Base Frequency	2.1 GHz
TDP	35 W
Package Specifications	
T <sub>JUNCTION</sub>	100°C
Processing Die Size	107 mm <sup>2</sup>
# of Processing Die Transistors	410 million
Sockets Supported	PGA478
Low Halogen Options Available	See MDDS
Advanced Technologies	
Intel® Turbo Boost Technology ‡	No
Intel® Virtualization Technology (VT-x) ‡	Yes
Intel® 64 ‡	Yes
Enhanced Intel SpeedStep® Technology	Yes
Intel® Platform Protection Technology	
Execute Disable Bit ‡	Yes

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PCN/MDDS Information

SLGLL

900799: PCN | MDDS

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Refer to Datasheet for formal definitions of product properties and features.

\*Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

"Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatinks/coolers.

See <http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading/hyper-threading-technology.html?wapkw=hyper+threading> for more information including details on which processors support Intel® HT Technology.

Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel® Turbo Boost Technology. See [www.intel.com/technology/turboboost/](http://www.intel.com/technology/turboboost/) for more information.

The Recommended Customer Price ("RCP") is pricing guidance for Intel products. Prices are for direct Intel customers and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet J5-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

For benchmarking data see <http://www.intel.com/performance>.

Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families. See <http://www.intel.com/content/www/us/en/processors/processor-numbers.html> for details.

Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIOS.

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